

L Number	Hits	Search Text	DB	Time stamp
1	6	((((257/635,700,758).CCLS.) or ((257/211,266,324).CCLS.)) and ((first adj wiring and second adj wiring) near layer)) and electrode and (multi-chip or multichip or multi near chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 08:40
2	2	("6274404").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 08:01
3	2	("6403463").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 08:01
4	1	((first adj wiring and second adj wiring) near layer) and electrode and (multi-chip or multichip or multi near chip)and conductive with bus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 08:44
6	0	((first adj wiring and second adj wiring) near layer) and electrode and (multi-chip or multichip or multi near chip)and conductive near5 bus) not (((first adj wiring and second adj wiring) near layer) and electrode and (multi-chip or multichip or multi near chip)and conductive with bus)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 08:44
5	1	((first adj wiring and second adj wiring) near layer) and electrode and (multi-chip or multichip or multi near chip)and conductive near5 bus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 09:17
7	16	electrode and (multi-chip or multichip or multi near chip)and conductive near5 bus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 09:17
-	3648	(257/635,700,758).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 14:56
-	1274	(257/211,266,324).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 12:53
-	2641	(438/118,622).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 12:53
-	3086	(438/128,129,216,261,591,593).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 12:54
-	4	'multiple-chip' and ((257/635,700,758).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 12:57
-	0	'multiple-chip' and ((257/211,266,324).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 12:57

-	0	'multiple-chip' and ((438/118,622).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 12:57
-	0	'multiple-chip' and ((438/128,129,216,261,591,593).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 12:57
-	224	'multiple-chip'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 14:10
-	1444	stack\$3 near chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 14:11
-	22	(stack\$3 near chip) and ((257/635,700,758).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 14:12
-	2	(stack\$3 near chip) and ((257/211,266,324).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 14:32
-	3	(stack\$3 near chip) and ((438/128,129,216,261,591,593).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 14:33
-	32	(stack\$3 near chip) and ((438/118,622).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 14:55
-	3648	(257/635,700,758).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 14:56
-	2	("5892276").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 14:59
-	2	("5939790").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 15:27
-	130	((257/635,700,758).CCLS.) and ((257/211,266,324).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 16:08
-	4792	((257/635,700,758).CCLS.) or ((257/211,266,324).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 16:08
-	888	((257/635,700,758).CCLS.) or ((257/211,266,324).CCLS.) and 'multi-chip' chips (stack\$3 near chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 16:09

-	5355	first adj wiring and second adj wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 16:10
-	2275	(first adj wiring and second adj wiring) near layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 16:11
-	189	((((257/635,700,758).CCLS.) or ((257/211,266,324).CCLS.)) and ((first adj wiring and second adj wiring) near layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 16:11
-	98	((((257/635,700,758).CCLS.) or ((257/211,266,324).CCLS.)) and ((first adj wiring and second adj wiring) near layer)) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 07:29